

KIS-INSU 128

Extruded High-Density Polystyrene Foam

DESCRIPTION

KIS-INSU 128 is a extruded polystyrene foam board which provides superior heat insulation and protection for construction uses. It is manufactured from polystyrene extrusion technology which produces a rigid and closed-cell structure with durability and hence enable it to comply with international specifications and standards.

RECOMMENDED USES

- Roof or ground floor insulation
- Vertical insulation
- Protection board from concrete pour or other trades

ADVANTAGES

- Manufactured under strict factory guidelines to ensure uniformity
- Superior heat insulation
- High compression strength
- Moisture resistance
- Not susceptible to attack from fungus
- Fire Retardant

TECHNICAL SPECIFICATION

KIS-INSU 128

		KISINSU128
Maximum Operating Temperature (Onset)		80°C
Compressive strength	ASTM 1621:1994	> 0.45 N/mm ²
Water absorption, average	ASTM C272:1996	< 0.15 %
Thermal conductivity	ASTM C518:1998	
a) Density		About 42 kg/m ³
b) Temperature of Hot Face		42 °C
c) Temperature of Cold Face		20 °C
d) Mean Temperature		31 °C
e) Thermal Conductivity		0.0371 W/m°K
		0.0319 Kcal/mh°K
Coefficient of Thermal Expansion		
a) a ₁ (25°C to 60°C)		145µm/m°C
b) a ₂ (95°C to 99.6°C)		25300 μm/m°C

PACKAGING



KIS-INSU 128 is supplied in two sizes

- 25mm thk x 600mm x 1200mm
- 50mm thk x 600mm x 1200mm

STORAGE

Store material away from direct sunlight at all times. For longer storage, use an opaque plastic sheet and ensure sufficient ventilation to prevent excessive temperature buildup.

IMPORTANT NOTES

Any information and/or specification contained herein is to the best of the company knowledge, true and accurate, it is always recommended that trial to be carried out to confirm suitability of use for all products, as no warranty is given or implied in connection with any recommendations and/or suggestions made by the company representatives, agents and/or distributors.

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